



### Product Summary

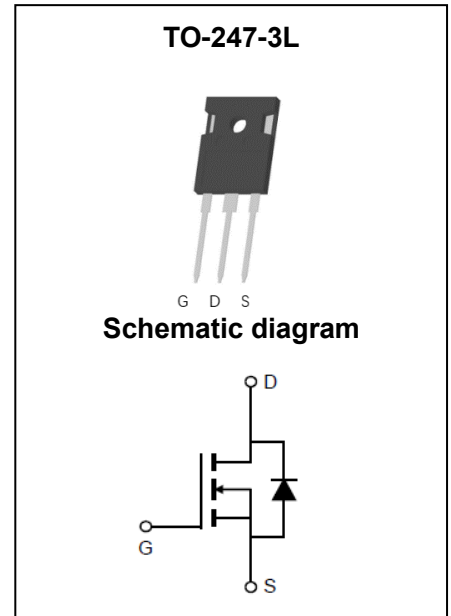
$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
200V	6.9m $\Omega$ @10V	125A

### Feature

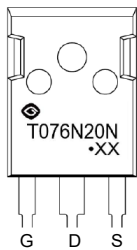
- Split Gate Trench Technology
- Low  $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

### Application

- DC/DC Converter
- Power Switching Application
- Motor Control



### MARKING:



T076N20N = Device Code  
 XX = Date Code  
 Solid Dot = Green Indicator

### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit	
Drain - Source Voltage	$V_{DS}$	200	V	
Gate - Source Voltage	$V_{GS}$	$\pm 20$	V	
Continuous Drain Current <sup>1</sup>	$T_C = 25^\circ\text{C}$	$I_D$	125	A
	$T_C = 100^\circ\text{C}$	$I_D$	81	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	500	A	
Single Pulsed Avalanche Current <sup>3</sup>	$I_{AS}$	93	A	
Single Pulsed Avalanche Energy <sup>3</sup>	$E_{AS}$	2162	mJ	
Power Dissipation <sup>5</sup>	$T_C = 25^\circ\text{C}$	$P_D$	284	W
Thermal Resistance from Junction to Ambient <sup>6</sup>	$R_{\theta JA}$	52	$^\circ\text{C}/\text{W}$	
Thermal Resistance from Junction to Case	$R_{\theta JC}$	0.44	$^\circ\text{C}/\text{W}$	
Junction Temperature	$T_J$	150	$^\circ\text{C}$	
Storage Temperature	$T_{STG}$	-55~ +150	$^\circ\text{C}$	

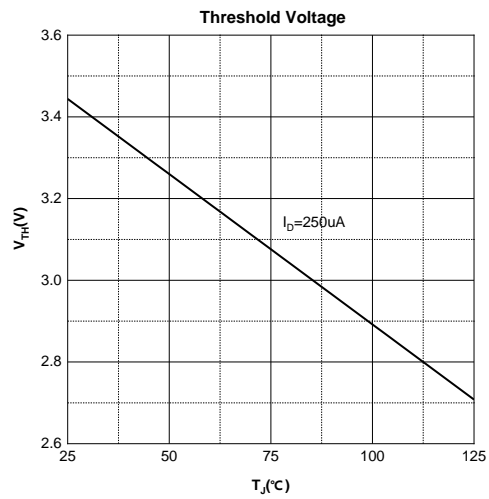
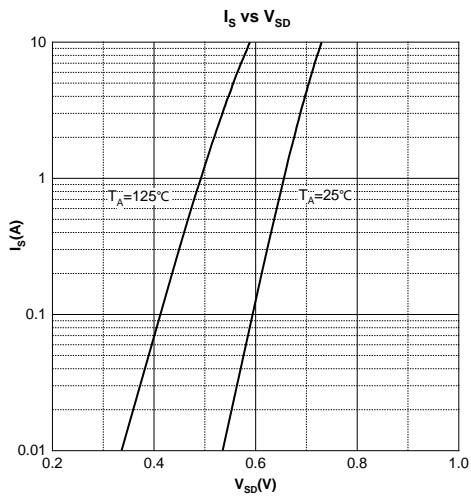
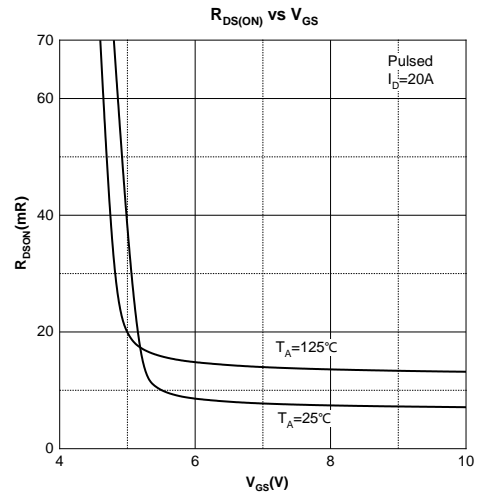
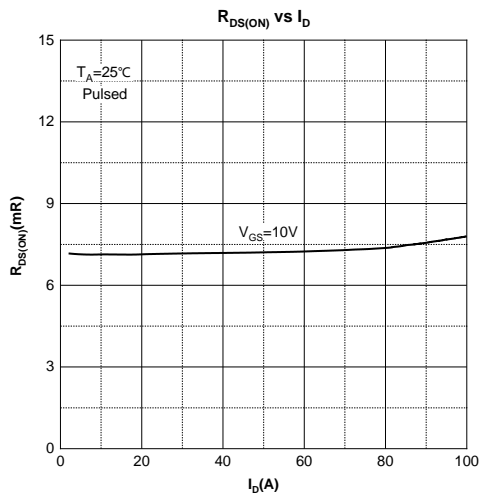
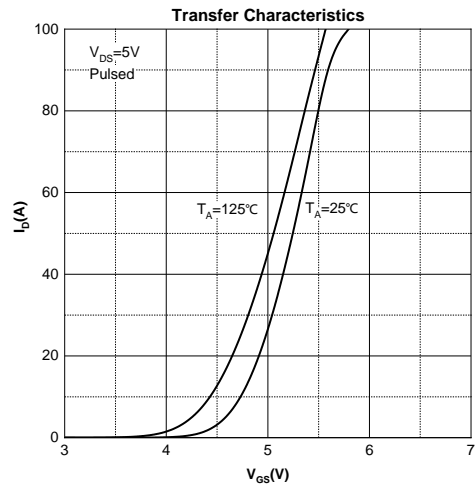
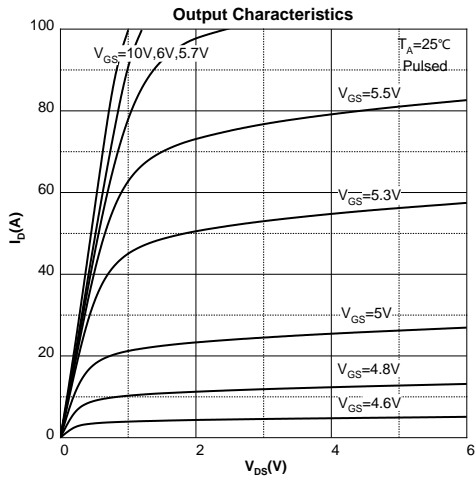
## MOSFET ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

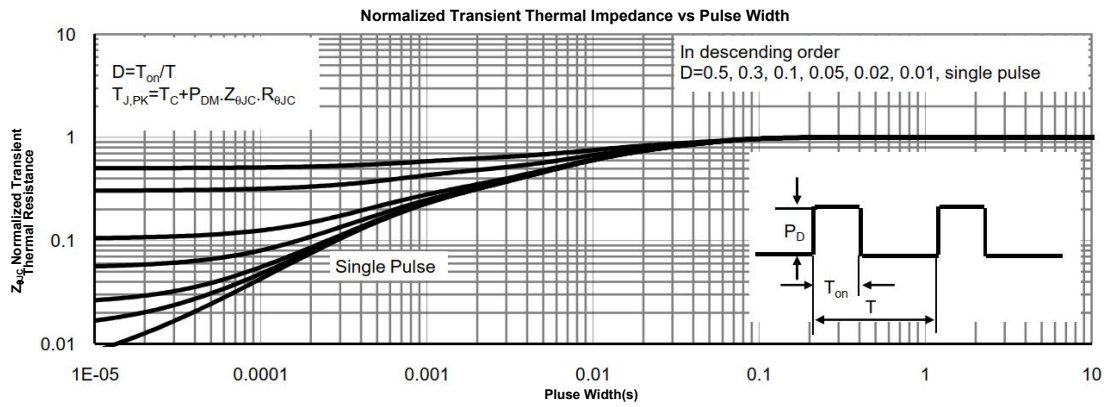
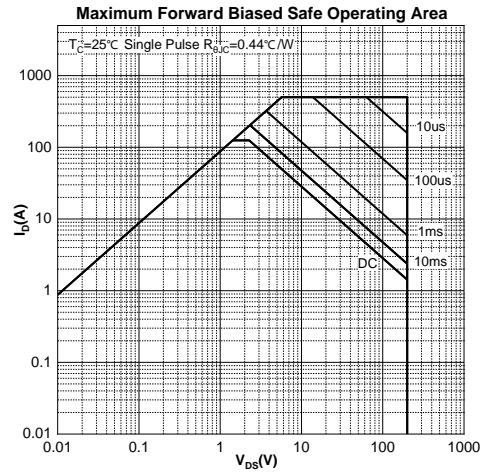
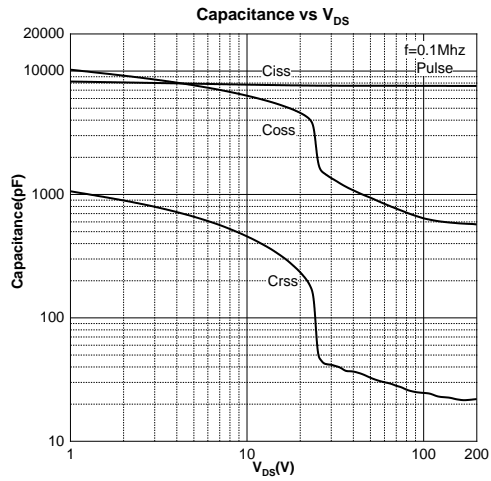
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drain - Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	200			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 200V, V_{GS} = 0V$			1	$\mu A$
Gate - Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
<b>On Characteristics<sup>4</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.5	3.4	4.5	V
Drain-source On-resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$		6.9	8.8	m $\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 100V, V_{GS} = 0V, f = 0.1MHz$		7614		pF
Output Capacitance	$C_{oss}$			639		
Reverse Transfer Capacitance	$C_{rss}$			28		
Gate Resistance	$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 0.1MHz$		1.9		$\Omega$
<b>Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{DS} = 100V, V_{GS} = 10V, I_D = 20A$		109		nC
Gate-source Charge	$Q_{gs}$			37		
Gate-drain Charge	$Q_{gd}$			24		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 100V, V_{GS} = 10V, I_D = 20A,$ $R_G = 4.7\Omega$		53		ns
Turn-on Rise Time	$t_r$			35		
Turn-off Delay Time	$t_{d(off)}$			62		
Turn-off Fall Time	$t_f$			14		
<b>Source - Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{SD}$	$V_{GS} = 0V, I_S = 20A$			1.2	V

### Notes :

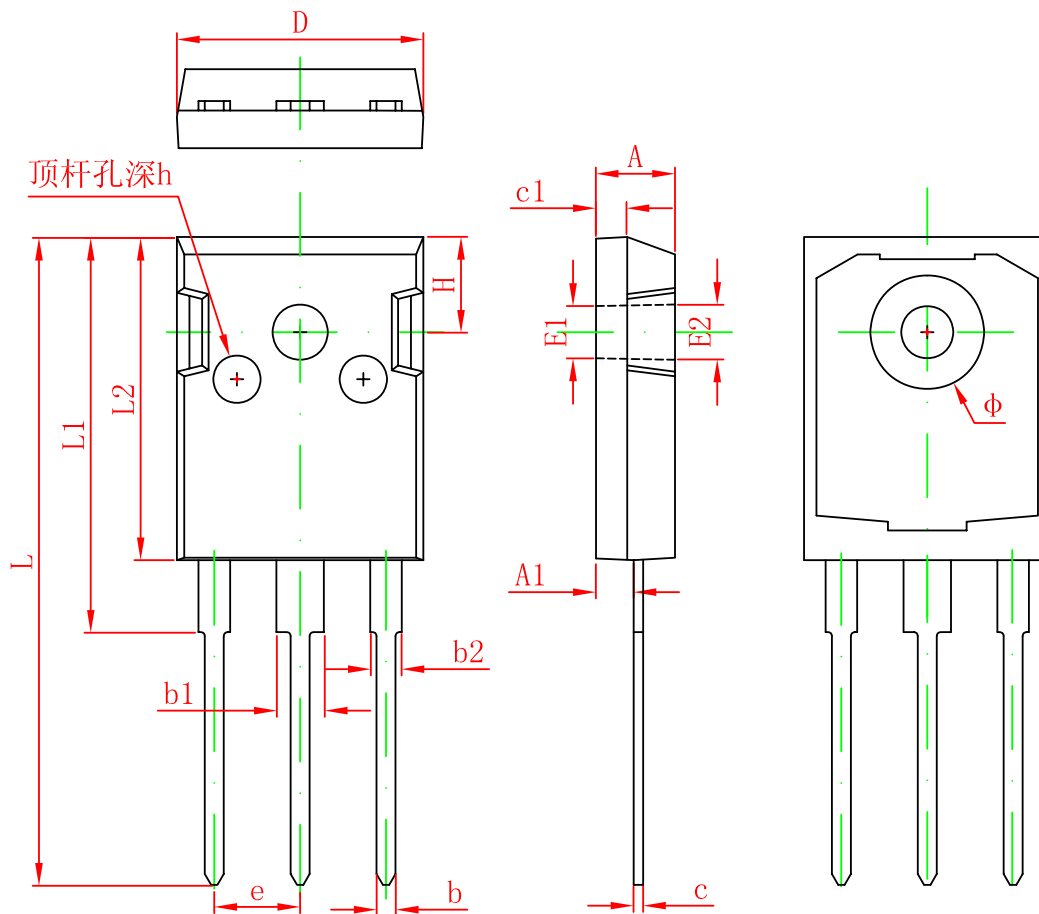
- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3.EAS condition:  $V_{DD} = 100V, V_{GS} = 10V, L = 0.5mH, R_G = 25\Omega$  Starting  $T_J = 25^\circ\text{C}$ .
- 4.Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 5.The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ\text{C}$ .And device mounted on a large heatsink
- 6.Device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

**Typical Characteristics**





## TO-247-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.850	5.150	0.191	0.200
A1	2.200	2.600	0.087	0.102
b	1.000	1.400	0.039	0.055
b1	2.800	3.200	0.110	0.126
b2	1.800	2.200	0.071	0.087
c	0.500	0.700	0.020	0.028
c1	1.900	2.100	0.075	0.083
D	15.450	15.750	0.608	0.620
E1	3.500 REF		0.138 REF	
E2	3.600 REF		0.142 REF	
L	40.900	41.300	1.610	1.626
L1	24.800	25.100	0.976	0.988
L2	20.300	20.600	0.799	0.811
$\Phi$	7.100	7.300	0.280	0.287
e	5.450 TYP		0.215 TYP	
H	5.980 REF		0.235 REF	
h	0.000	0.300	0.000	0.012